

Session: WE4C

Micromachining for Microwave and Millimeter Wave Applications

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The emerging application of micromachining technology is presented. This technology uses bulk processes in silicon, GaAs or piezoelectric materials, very thin dielectric membrane structures, micro-electromechanical surface actuators or thick polyamide structures to build novel low loss, and low cost microwave and mm-wave components. The components realized so far include wideband low loss switches, wideband couplers and baluns, power dividers, very low loss planar and cavity like filters for cellular and satellite communications, and high efficiency integrated antennas and receivers for millimeter wave and sub-millimeter wave applications.

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